



N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I _D (A) ^{a,g}	Q _g (Typ.)		
30	0.0068 at V _{GS} = 10 V	16	13.2 nC		
	0.0097at V _{GS} = 4.5 V	16	13.2110		

PowerPAK® SO-8 6.15 mm

Ordering Information:

SiRA16DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

Bottom View

FEATURES

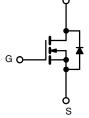
- TrenchFET® Gen IV Power MOSFET
- 100 % R_a and UIS Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



COMPLIANT **HALOGEN**

APPLICATIONS

- DC/DC Conversion
- High Current Power Rails in Computing
- Load Switching
- **Battery Protection**
- DC/AC Inverters



N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	30	V		
Gate-Source Voltage	V _{GS}	+ 20, - 16	7 '		
	T _C = 25 °C		16 ^g		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	_	16 ^g		
Continuous Diain Current (1) = 150 C)	T _A = 25 °C	I _D	16 ^{b, c}		
	T _A = 70 °C		14.2 ^{b, c}	Α Α	
Pulsed Drain Current (t = 100 μs)	1	I _{DM}	70	_ ^	
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	16 ^g		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.5 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	15		
Single Pulse Avalanche Energy		E _{AS}	11.25	mJ	
	T _C = 25 °C		29.7		
Maximum Dawar Dissination	T _C = 70 °C	P _D	19	w	
Maximum Power Dissipation	T _A = 25 °C	LD	3.9 ^{b, c}		
	T _A = 70 °C		25 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperatur	_	260			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 10 s	R_{thJA}	27	32	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	3.5	4.2	0/ **	

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 70 °C/W.
- g. Package limited.

Document Number: 62901 S13-2078-Rev. A, 30-Sep-13 For technical questions, contact: pmostechsupport@vishay.com

www.vishay.com

SiRA16DP

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Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static			1	1 71			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			18			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		2.3	V	
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = + 20, - 16 V			± 100	nA	
•		V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS} –	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
		V _{GS} = 10 V, I _D = 15 A		0.0056	0.0068		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$			0.0097	7 Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 15 A		60		S	
Dynamic ^{b, d}			<u> </u>	<u> </u>			
Input Capacitance	C _{iss}			2060			
Output Capacitance	C _{oss}	V 45VV 0V/ 4MI-		543		pF	
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		47			
C _{rss} /C _{iss} Ratio				0.023	0.046		
T	0	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A		31	47		
Total Gate Charge	Qg	V 15VV 45VI 10A		13.2	20		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		5.7		nC	
Gate-Drain Charge	Q_{gd}			2.2			
Output Charge	Q _{oss}	V _{DS} = 15 V, V _{GS} = 0 V		15.4			
Gate Resistance	R_{g}	f = 1 MHz	0.4	1.0	1.7	Ω	
Turn-On Delay Time	t _{d(on)}			21	42		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		19	38	1	
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			10	20	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		19	38		
Fall Time	t _f			8	16	1	
Drain-Source Body Diode Characteristic			•	•			
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			16	۸	
Pulse Diode Forward Current (t = 100 μs)	I _{SM}				70	Α	
Body Diode Voltage	V_{SD}	I _S = 5 A		0.78	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			28	55	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 5 A$, $dI/dt = 100 A/\mu s$,		20	40	nC	
Reverse Recovery Fall Time	t _a	$T_J = 25 ^{\circ}C$		14		ns	
Reverse Recovery Rise Time	t _b			14			

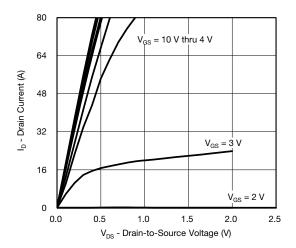
Notes:

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

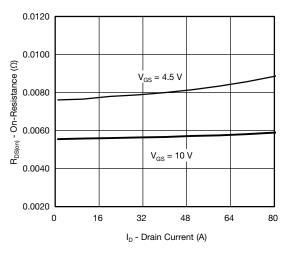
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



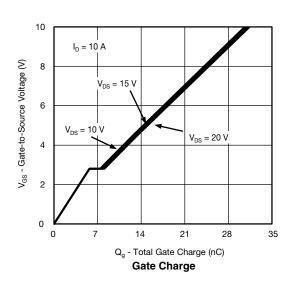
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

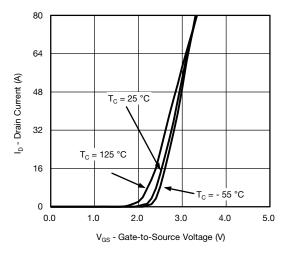


Output Characteristics

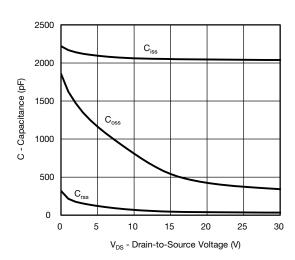


On-Resistance vs. Drain Current

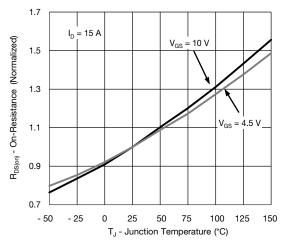




Transfer Characteristics



Capacitance

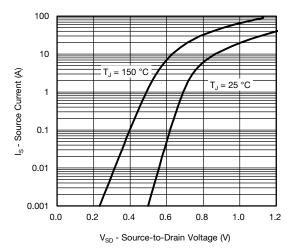


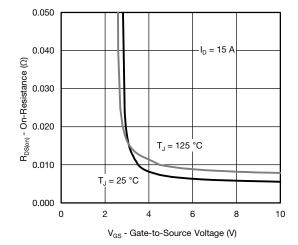
On-Resistance vs. Junction Temperature

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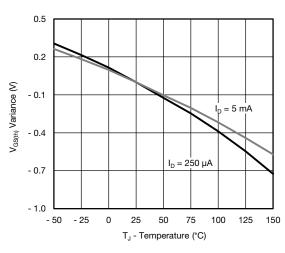
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

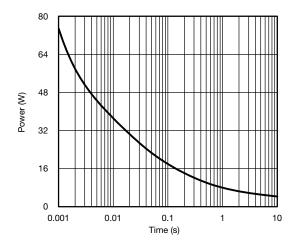




Source-Drain Diode Forward Voltage

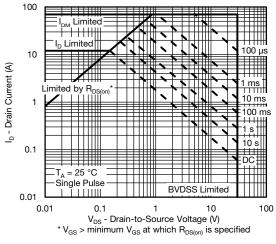
On-Resistance vs. Gate-to-Source Voltage





Threshold Voltage

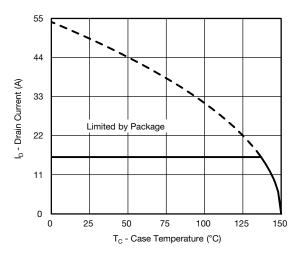
Single Pulse Power, Junction-to-Ambient



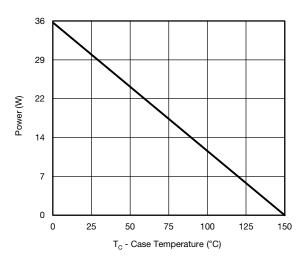
Safe Operating Area



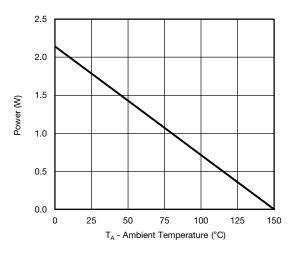
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*







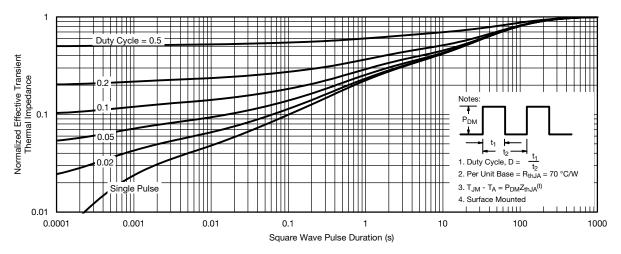
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

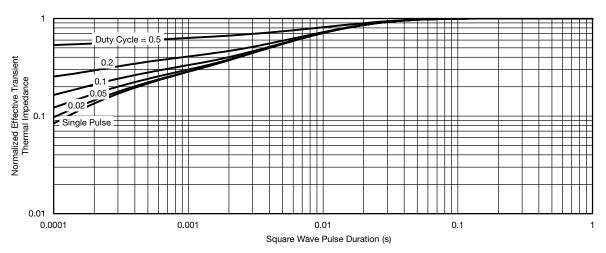
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

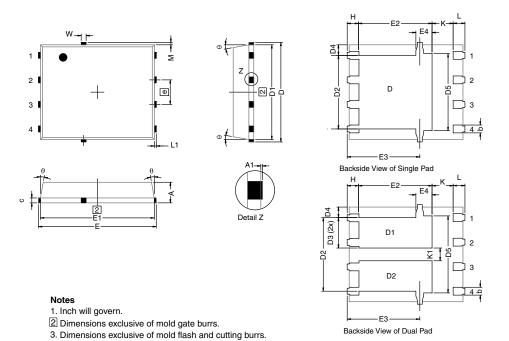


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62901.

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PowerPAK® SO-8, (Single/Dual)



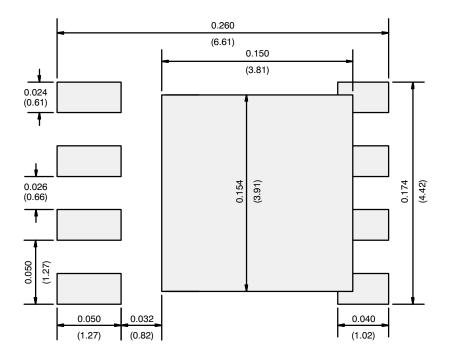
DIM.		MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	0.97	1.04	1.12	0.038	0.041	0.044		
A1		-	0.05	0	-	0.002		
b	0.33	0.41	0.51	0.013	0.016	0.020		
С	0.23	0.28	0.33	0.009	0.011	0.013		
D	5.05	5.15	5.26	0.199	0.203	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.56	3.76	3.91	0.140	0.148	0.154		
D3	1.32	1.50	1.68	0.052	0.059	0.066		
D4		0.57 typ.			0.0225 typ.			
D5		3.98 typ.		0.157 typ.				
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	5.79	5.89	5.99	0.228	0.232	0.236		
E2	3.48	3.66	3.84	0.137	0.144	0.151		
E3	3.68	3.78	3.91	0.145	0.149	0.154		
E4		0.75 typ.		0.030 typ.				
е		1.27 BSC		0.050 BSC				
K		1.27 typ.		0.050 typ.				
K1	0.56	-	-	0.022	-	-		
Н	0.51	0.61	0.71	0.020	0.024	0.028		
L	0.51	0.61	0.71	0.020	0.024	0.028		
L1	0.06	0.13	0.20	0.002	0.005	0.008		
θ	0°	-	12°	0°	-	12°		
W	0.15	0.25	0.36	0.006	0.010	0.014		
М		0.125 typ.			0.005 typ.			

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DWG: 5881



RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE

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